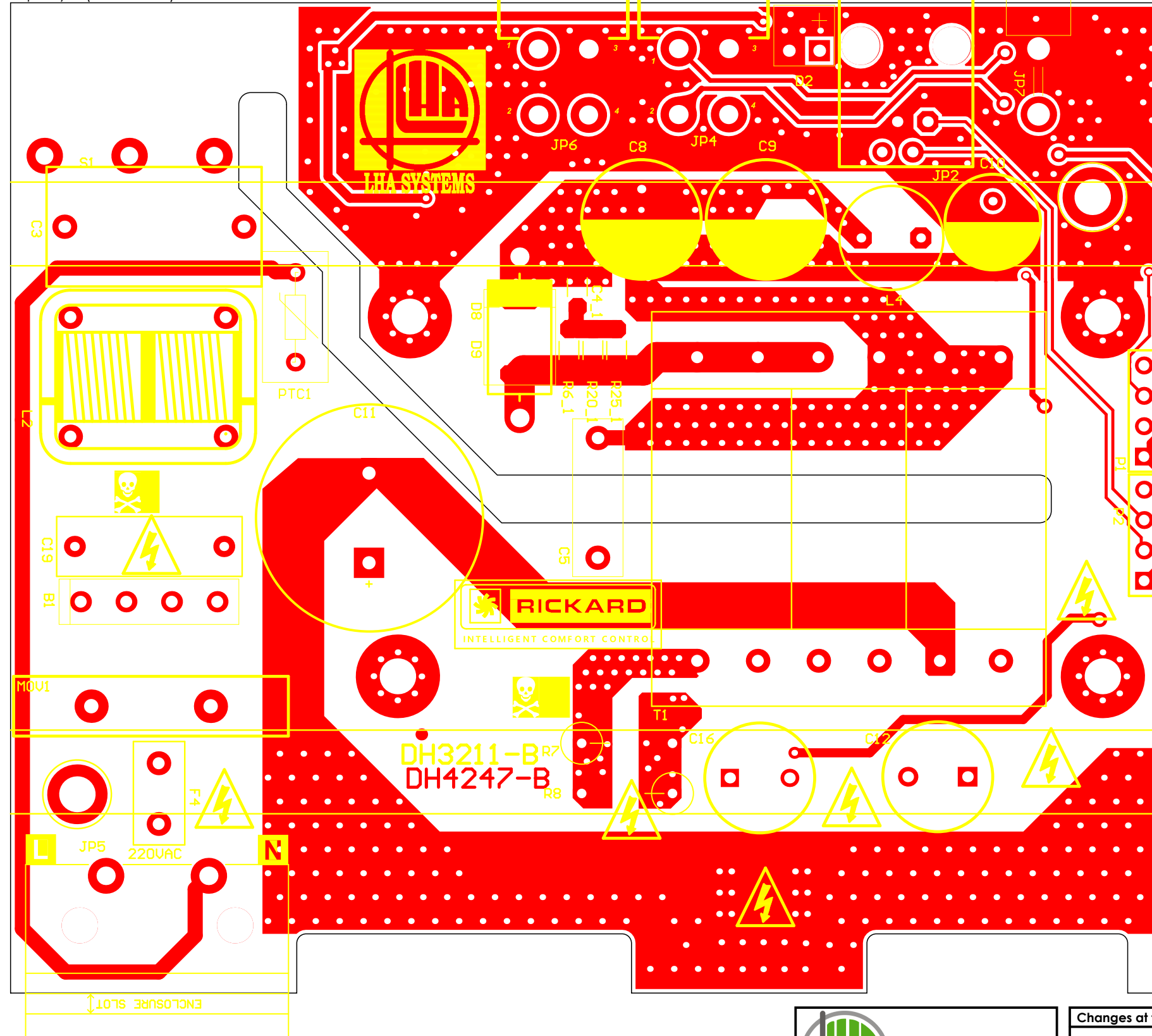


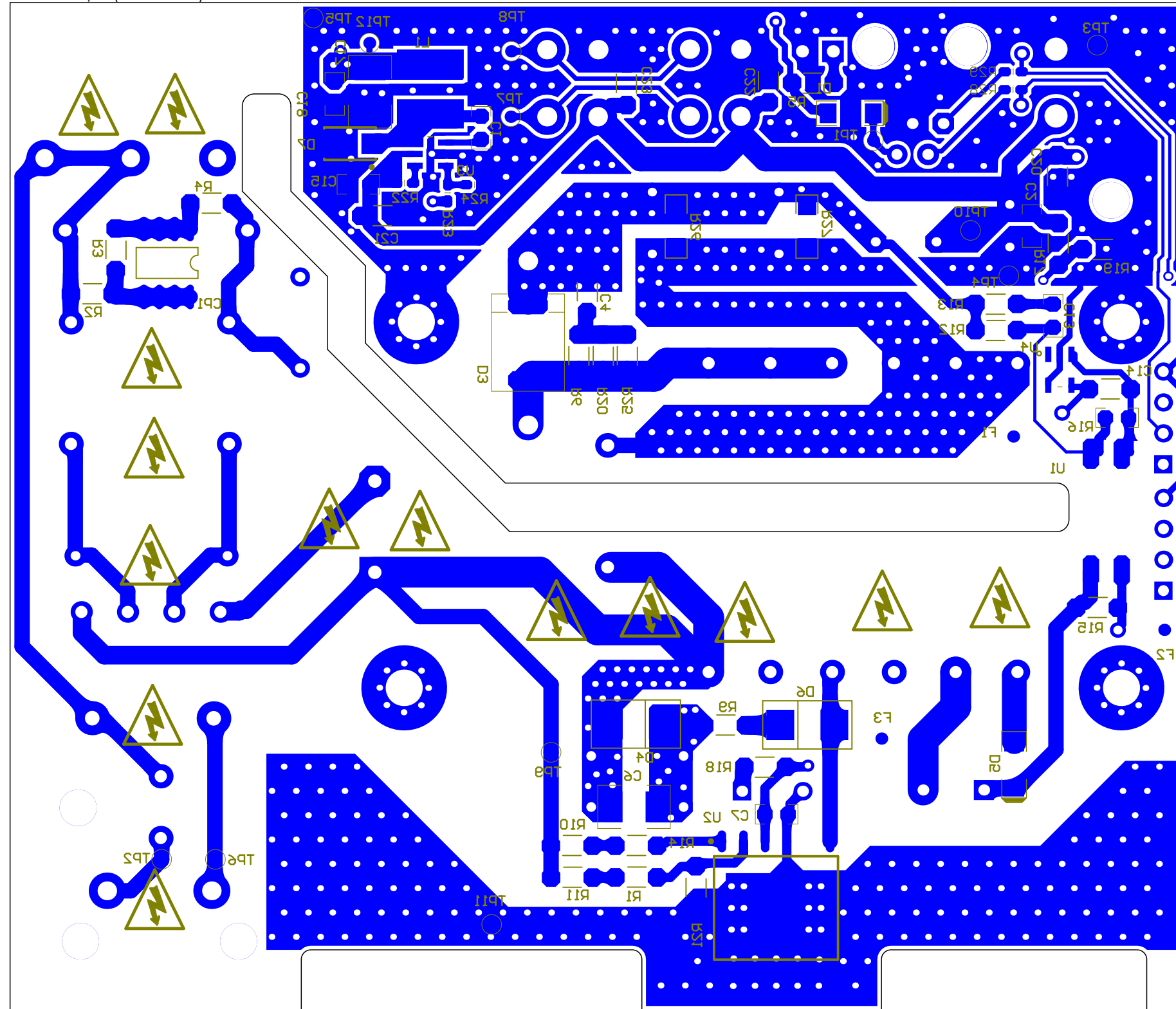
Top Layer (Scale 2.5:1)



LHA SYSTEMS
 1 INNOVATION CENTRE II
 TECHNOPARK
 STELLENBOSCH
 7600
 SOUTH AFRICA
 +27-21-880-1886

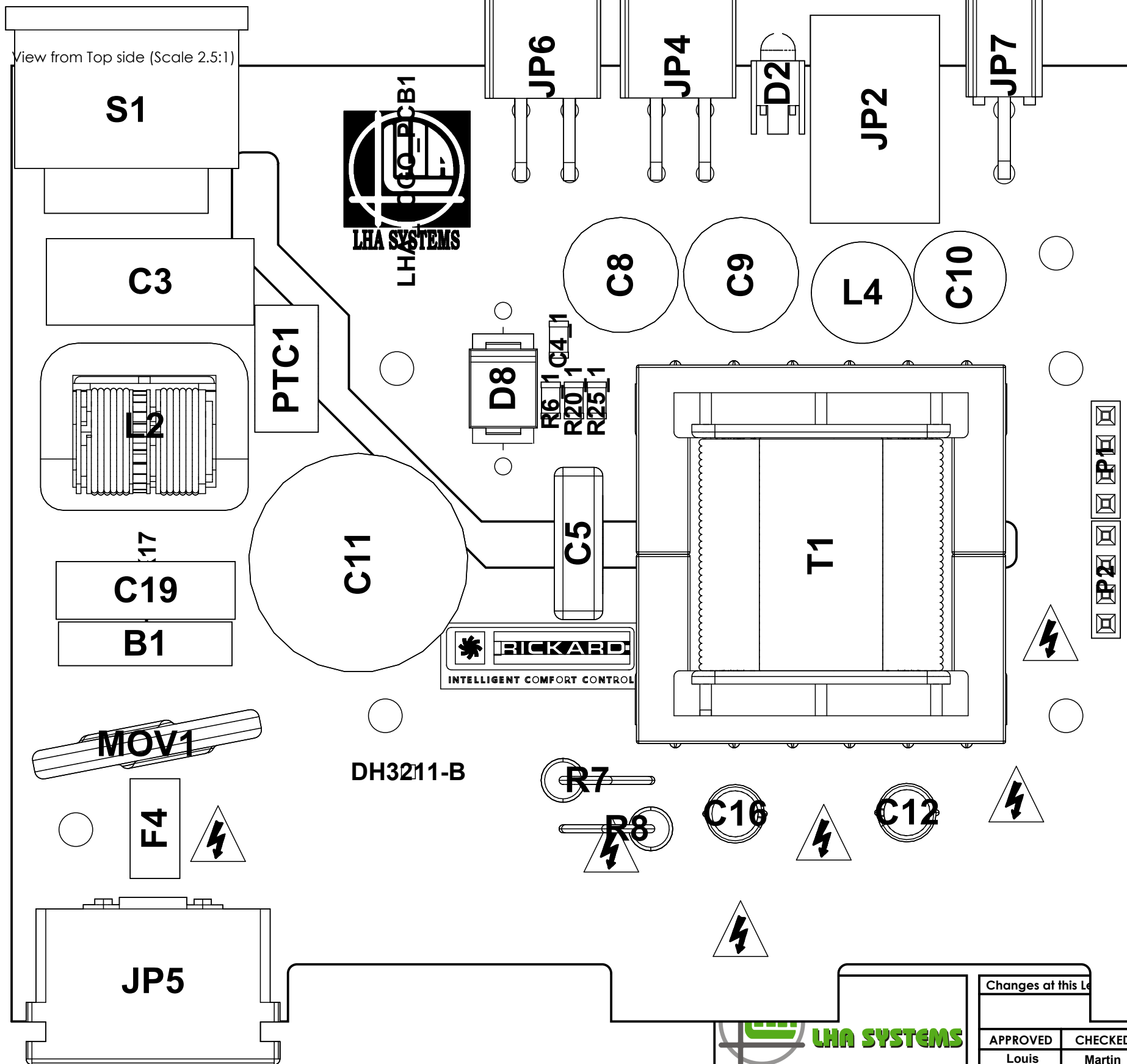
Changes at this Level					
APPROVED	CHECKED	DRAWN	ECP No.	ISSUE	DATE
Louis	Martin	Martin	None	B	27/08/2021
Variant					Build
No Variations					[1]
TITLE: Assembly PCB, PSU IPSU eSOP					
DOC No: DH 32 11 - B					
File Name: DH.PCBDwf					SHEET: 1 OF 4

Bottom Layer (Scale 2.5:1)



LHA SYSTEMS
 1 INNOVATION CENTRE II
 TECHNOPARK
 STELLENBOSCH
 7600
 SOUTH AFRICA
 +27-21-880-1886

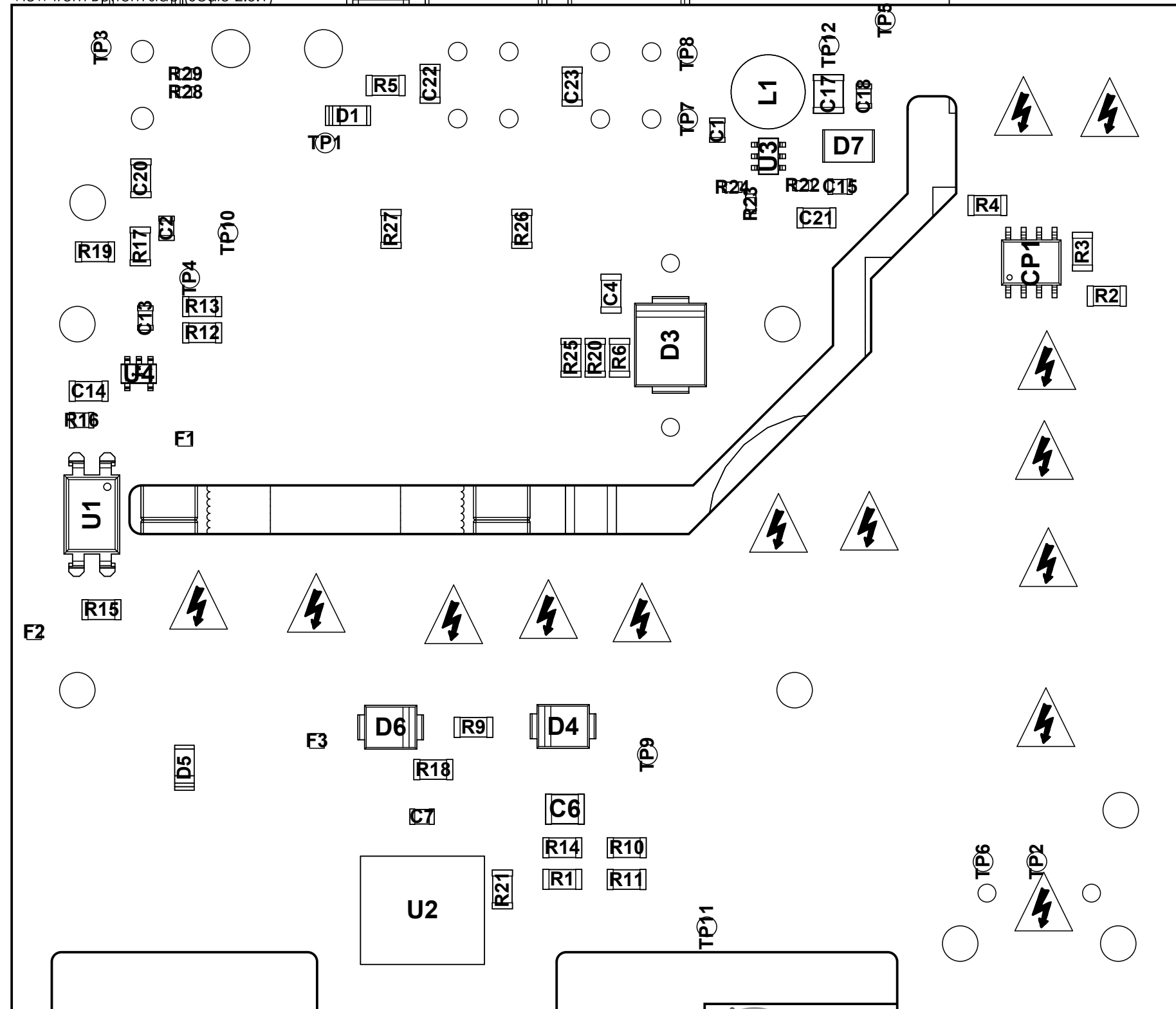
Changes at this Level					
APPROVED	CHECKED	DRAWN	ECP No.	ISSUE	DATE
Louis	Martin	Martin	None	B	27/08/2021
Variant					Build
No Variations					[1]
TITLE: Assembly PCB, PSU IPSU eSOP					
DOC No: DH 32 11 - B					
File Name: DH.PCBDwf					SHEET: 2 OF 4



LHA SYSTEMS
 1 INNOVATION CENTRE II
 TECHNOPARK
 STELLENBOSCH
 7600
 SOUTH AFRICA
 +27-21-880-1886

Changes at this Level					
APPROVED	CHECKED	DRAWN	ECP No.	ISSUE	DATE
Louis	Martin	Martin	None	B	27/08/2021
Variant					Build
No Variations					[1]
TITLE: Assembly PCB, PSU IPSU eSOP					
DOC No: DH 32 11 - B					
File Name: DH.PCBDwf					SHEET: 3 OF 4

View from Bottom side (Scale 2.5:1)



LHA SYSTEMS
 1 INNOVATION CENTRE II
 TECHNOPARK
 STELLENBOSCH
 7600
 SOUTH AFRICA
 +27-21-880-1886

APPROVED	CHECKED	DRAWN	ECP No.	ISSUE	DATE
Louis	Martin	Martin	None	B	27/08/2021
Variant					Build
No Variations					[1]
TITLE: Assembly PCB, PSU IPSU eSOP					
DOC No: DH 32 11 - B					
File Name: DH.PCBDwf					SHEET: 4 OF 4